



RECC

05-20-2002



102095540

COVER SHEET

To the Honorable Commissioner of Patents a

d original documents or copy thereof.

1. Name of conveying party(ies): 5-10-02
Philip R. Laws, Jon Worthington
Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):
Name: 3Dlabs Inc., Ltd.

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other

Address: Reid Hall, Hamilton HM11, Bermuda
Additional name(s) & address(es) attached? Yes No

Execution Date: May 1, 2002

4. Application number(s) or patent number(s): (Atty.Docket TD-164)
If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)
10/071,895

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Robert Groover
17000 Preston Rd. #230,
Dallas TX 75248
(972) 380-6333

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$40
 Enclosed
 Authorized to be charged to deposit account

8. Deposit account number:
07-2320
(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert Groover
Name of Person Signing

[Signature]
Signature

5/1/02
Date

Total number of pages including cover sheet, attachments, and document: 3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments

05/15/2002 STEUMEL1 00000041 10071895

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ASSIGNMENT

As a below-named inventor of the U.S. patent application entitled **Rasterizer Edge Function Optimizations**, which names an inventorship of Philip R. Laws and Jon Worthington, and which was filed 02/08/2002 (MM/DD/YY) and received Serial No. 10/071,895, I hereby sell, assign and transfer to **3Dlabs Inc., Ltd.**, Reid Hall, Hamilton HM11, Bermuda, (hereinafter referred to as ASSIGNEE), for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the full and exclusive right, title and interest to said invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in all foreign countries to be obtained for said invention by said application or any division, continuation, continuation-in-part, renewal, substitute, extension, re-examination or reissue thereof or any legal equivalent thereof in any foreign country for the full term or terms of which the same may be granted, and specifically including the right to file foreign applications and claim priority therefor under the provisions of any convention or treaty;

and I also hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

and I further hereby covenant that I will, upon ASSIGNEE'S request, promptly provide ASSIGNEE with all pertinent facts and documents, relating to said application, to any invention disclosed therein, or to any of said Letters Patent or legal equivalents thereof in the United States or in foreign countries, as may be known and accessible to me, and that I will testify and give evidence as to the same in any litigation or interference which may arise, and that I will promptly execute and deliver to ASSIGNEE or its legal representative, without charge but at Assignee's expense, any and all papers, instruments or affidavits which may be required, necessary or desirable for the purpose of applying for, obtaining, maintaining, issuing or enforcing said application and said Letters Patent and said equivalents thereof in the United States or in any foreign country; and I further authorize ASSIGNEE or its legal representative to make any submissions or true declarations which may be needed in connection with the prosecution of this application or related applications in the U.S. or in other countries, consistent with the requirements of the applicable country;

AND I HEREBY AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on said invention to ASSIGNEE, its successors and assigns.

IN WITNESS WHEREOF, this Assignment has been executed on the date set forth below.

Inventor's Name: Philip R. Laws

Signature: Philip R. Laws

Residence Address: 19 The Oaks, Moormede Crescent, Staines, Middlesex TW18 4SH,
United Kingdom

Today's Date, and Date Application Signed: 1st May 2002

Inventor's Name: Jon Worthington

Signature: J. Worthington

Residence Address: 4 Lea Way, Bcarwood, Bournemouth, Dorset BF11 9NF,
United Kingdom

Today's Date, and Date Application Signed: 1st MAY 2002

ASSIGNMENT

As a below-named inventor of the U.S. patent application entitled **Rasterizer Edge Function Optimizations**, which names an inventorship of Philip R. Laws and Jon Worthington, and which was filed 02/08/2002 (MM/DD/YY) and received Serial No. **10/071,895**, I hereby sell, assign and transfer to **3Dlabs Inc., Ltd.**, Reid Hall, Hamilton HM11, Bermuda, (hereinafter referred to as ASSIGNEE), for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the full and exclusive right, title and interest to said invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in all foreign countries to be obtained for said invention by said application or any division, continuation, continuation-in-part, renewal, substitute, extension, re-examination or reissue thereof or any legal equivalent thereof in any foreign country for the full term or terms of which the same may be granted, and specifically including the right to file foreign applications and claim priority therefor under the provisions of any convention or treaty;

and I also hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

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Inventor's Name: Jon Worthington

Signature: Jon Worthington

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United Kingdom

Today's Date, and Date Application Signed: 1st MAY 2002